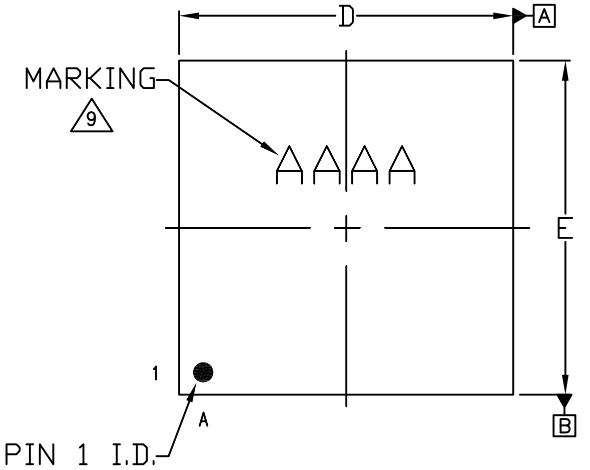
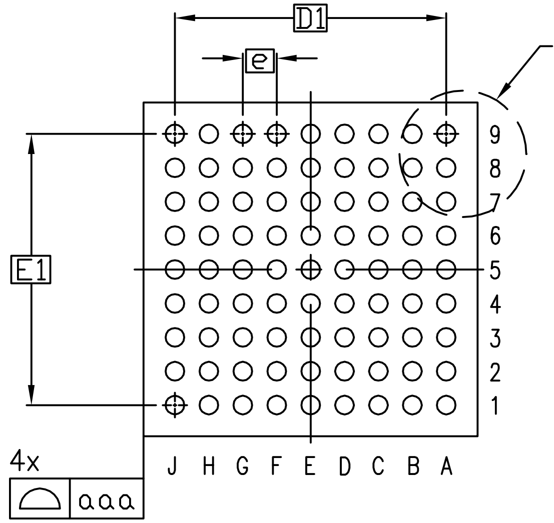
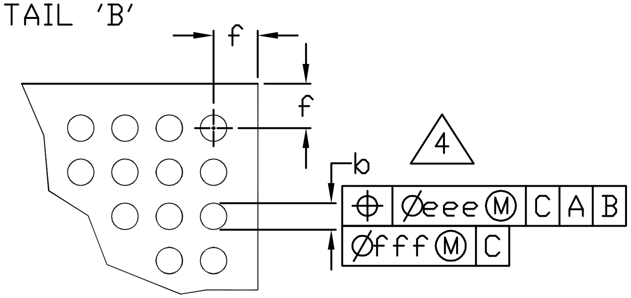


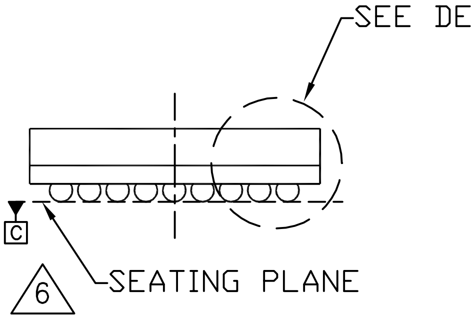
TOP VIEW



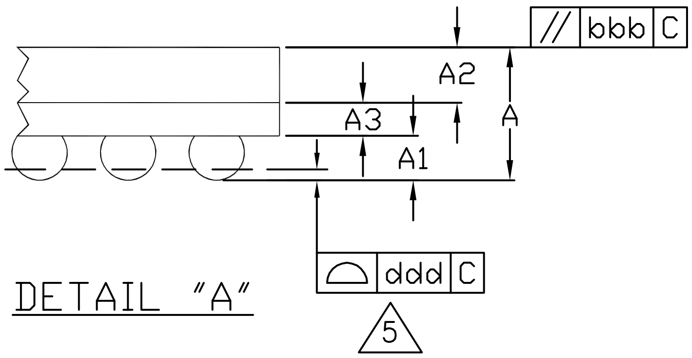
BOTTOM VIEW



DETAIL "B"



SIDE VIEW



DETAIL "A"

DIMENSIONAL REFERENCES			
REF.	MIN.	NOM.	MAX.
A	1.08	1.20	1.32
A1	0.36	---	0.46
A2	0.53 REF		
A3	0.26 REF		
D	9.90	10.00	10.10
D1	8.00 BSC		
E	9.90	10.00	10.10
E1	8.00 BSC		
b	0.44	0.54	0.64
e	1.00 BSC		
f	0.90	1.00	1.10
aaa	--	--	0.20
bbb	--	--	0.35
ddd	--	--	0.10
eee	--	--	0.25
fff	--	--	0.10
M	9		
N	81		
Pkg. Code	X8100-2, X8100-3		

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. 'e' REPRESENTS THE BASIC SOLDER BALL GRID PITCH.
3. 'M' REPRESENTS THE BASIC SOLDER BALL MATRIX SIZE AND SYMBOL 'N' IS THE NUMBER OF BALLS AFTER DEPOPULATING.
4. 'b' IS MEASURABLE AT THE MAXIMUM SOLDER BALL DIAMETER AFTER REFLOW PARALLEL TO PRIMARY DATUM C .
5. DIMENSION 'ddd' IS MEASURED PARALLEL TO PRIMARY DATUM C .
6. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
7. PACKAGE SURFACE SHALL BE MATTE FINISH.
8. SUBSTRATE MATERIAL BASE IS BT RESIN.
9. MARKING SHOWN IS FOR PKG. ORIENTATION ONLY.
10. MATERIAL MUST COMPLY WITH BANNED AND RESTRICTED SUBSTANCES SPEC #10-0131.
11. ALL DIMENSIONS APPLY TO BOTH LEADED (-) AND PbFREE (+) PKG. CODES.

-DRAWING NOT TO SCALE-

MAXIM

TITLE:
PACKAGE OUTLINE,
81 BALLS CSBGA, 10x10x1.2mm

APPROVAL	DOCUMENT CONTROL NO.	REV.	
EDEN CHEN 10/26/11	21-0394	D	1/1